

# **IPC-2591-Version 1.7**

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## **Connected Factory Exchange (CFX)**

Supersedes IPC-2591-Version 1.6  
March 2023

*An international standard developed by IPC*



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## IPC-2591-Version 1.7

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Developed by the IPC-CFX Standard Task Group (2-17a) of the  
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Users of this publication are encouraged to participate in the  
development of future revisions.

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